

## **R E M A R K S**

Claims 1, 2, 4-7, 11-14 and 19-21 are in the application, with Claims 1, 4, 11-14 and 19 having been amended, and with Claims 3, 8-10 and 15-18 having been cancelled. Claims 1, 10 and 19 are the independent claims herein. No new matter has been added. Reconsideration and further examination are respectfully requested.

The abstract has now been amended to respond to the Examiner's objection thereto.

### **Claim Rejections Under 35 USC § 102(e)**

Claim 1 is rejected as being anticipated by Chen, U.S. Patent No. 6,639,804 ("Chen"). Since claim 1 has been amended to incorporate the limitations of claims 3, and also to add other limitations, the rejection of claim 3 under 35 USC § 103(a) based on Chen and Lee (U.S. Patent No. 6,097,601) is also pertinent.

As now presented, claim 1 is directed to a "method" which includes "providing a circuit board having a plurality of holes formed therethrough" and "mounting a spring to an underside of the circuit board", where "the mounted spring ha[s] a plurality of holes each aligned with a respective one of the holes in the circuit board". Claim 1 further recites that "the spring includes a plurality of bosses, each having one of the holes of the spring formed therethrough". The method of claim 1 further includes "sandwiching each of the bosses of the spring between a respective chassis standoff and a respective heat sink standoff". Finally, claim 1 recites that "said circuit board holes are shaped and sized so that said circuit board is not sandwiched between said chassis standoffs and said heat sink standoffs".

The latter feature of claim 1, namely that the holes in the circuit board are such that the circuit board is not sandwiched between the chassis standoffs and the heat sink standoffs, is supported at FIG. 7 of the present application (hole 32 large enough not to bind heat sink standoff 38 or chassis standoff 16, boss 62 of spring 18 sandwiched between standoffs 38, 16) and at page 9, lines 17-24 of the specification. As explained at page 10, lines 1-8 of the specification, since the circuit board is not bound between the standoffs, it effectively floats at the locus of the IC 28, so that the spring 18, pressing upwardly on the lower surface of the circuit

board, keeps the IC 28 in contact with the heat sink 36. This feature (holes in circuit board so that the circuit board is not sandwiched between heat sink and chassis standoffs) is not shown in the prior art. In particular, referring to FIG. 1 of the Chen reference, there is no provision in the circuit board 30 for allowing chassis and heat sink standoffs to meet without sandwiching the circuit board 30 therebetween. There is nothing in Chen to suggest that the circuit board holes shown therein are any wider than required to accommodate fasteners. It is accordingly submitted that claim 1, at least as now presented, is allowable over the prior art relied upon by the Examiner.

Claims 2 and 4-7 are dependent on claim 1 and are submitted as patentable on the same basis as claim 1. Independent claim 19 has been amended in like fashion to claim 1 to recite that the circuit board is not sandwiched between the chassis and heat sink standoffs. Claim 19 is therefore believed allowable on the same basis as claim 1, as are the dependent claims of claim 19 (i.e., claims 20 and 21).

#### **Claim Rejections Under 35 USC § 103(a)**

Claims 11-13 are rejected as being unpatentable over Chen in view of Lee.

Claim 11 has been rewritten in independent form, with the additional claim limitation that the eight sides recited therein together form a closed octagonal loop. Support for this limitation is found at FIG. 3. It is believed that such a closed loop configuration is not suggested by either element 10 of the Chen reference (being a substantially solid plate) or element 20 of the Lee reference (being an I-shaped frame) nor from their combination. It is therefore respectfully requested that the rejection of claim 11 be reconsidered and withdrawn.


Claims 12-14 are dependent on claim 11 and are submitted as patentable on the same basis as claim 11.

**CONCLUSION**

Accordingly, Applicants respectfully request allowance of the pending claims. If any issues remain, or if the Examiner has any further suggestions for expediting allowance of the present application, the Examiner is kindly invited to contact the undersigned via telephone at (203) 972-3460.

Respectfully submitted,

August 5, 2005  
Date

  
\_\_\_\_\_  
Nathaniel Levin  
Registration No. 34,860  
Buckley, Maschoff & Talwalkar LLC  
Five Elm Street  
New Canaan, CT 06840  
(203) 972-3460